

WHAT IS CLAIMED IS:

1. A circuit substrate comprising:  
an insulating base;  
wiring layers provided disposed on said insulating  
base; and  
a conductor provided disposed inside said insulating  
base to electrically connect between said wiring layers  
in an interlayer of said insulating base,  
wherein a bonding strength between said wiring  
layers and said conductor is compared with a bonding  
strength between said wiring layers and said insulating  
base to be relatively lowered the latter.
2. The circuit substrate according to claim 1, wherein  
said conductor contains a resin composition, and a  
relative relationship of said bonding strength is  
established by comparing a glass transition temperature  
of the resin composition with a glass transition  
temperature of a resin composition constituting a surface  
site of said insulating base to set the latter higher.
3. The circuit substrate according to claim 1, wherein  
said insulating base and said conductor contain a  
thermosetting epoxy resin composition, and the relative  
relationship of said bonding strength is established by  
comparing a volume content of the thermosetting epoxy  
resin in said conductor with a volume content of the  
thermosetting epoxy resin in said insulating base to set  
the latter lower.
4. The circuit substrate according to claim 1, wherein  
the bonding strength between said wiring layers and said  
insulating base is a bonding strength between said wiring  
layers and said insulating base in an adjacency of said  
conductor.
5. The circuit substrate according to claim 1, wherein

the relative relationship of said bonding strength is established by forming a metal cohesion between said conductor and said wiring layers.

6. The circuit substrate according to claim 1, wherein the relative relationship of said bonding strength is established by providing a non-bonded region at a part of a bonding site between said wiring layers and said insulating base in the adjacency of said conductor.

7. The circuit substrate according to claim 1, wherein the relative relationship of said bonding strength is established by providing a region containing an uncured resin component at a bonding site between said wiring layers and said insulating base in the adjacency of said conductor.

8. The circuit substrate according to claim 1, wherein the relative relationship of said bonding strength is established by forming an irregularity at a bonding site between said conductor and said wiring layers.

9. A circuit substrate comprising:

an insulating base; and

a conductor provided inside said insulating base to electrically connect an interlayer of said insulating base,

wherein a tensile strength of said conductor in a base thickness direction is compared with a bonding strength between said conductor and said insulating base on a wall surface of said conductor to set the latter relatively lower.

10. A manufacturing method of a circuit substrate, comprising the steps of:

preparing a first wiring layer in which one surface thereof is supported by a first supporting base and at least another surface thereof is provided with an

antioxidant layer, and laminating the first wiring layer and an insulating base via a bonding layer in a state that said another surface is in contact with said insulating base;

5        forming a through hole in said insulating base to reach said first wiring layer, and selectively removing said antioxidant layer exposed on a bottom of said through hole;

          filling said through hole with a conductor;

10        laminating a conductor foil or a second wiring layer supported by a second supporting base onto a surface of said insulating base where said first wiring layer is not placed ; and

15        laminating and integrating said first wiring layer, said insulating base, and said conductor foil / said second wiring layer by heating and pressurizing in a thickness direction thereof, and forming a metal cohesion between said conductor and said first wiring layer and between said conductor and said conductor foil / said second wiring layer.

20        11. A manufacturing method of a circuit substrate, comprising the steps of:

25        preparing a first wiring layer in which one surface thereof is supported by a first supporting base, and laminating the first wiring layer and an insulating base via an adhesive layer in a state that an another surface of said first wiring layer is in contact with said insulating base;

30        forming a through hole in said insulating base to reach said first wiring layer;

          filling said through hole with a conductor containing a conductive powder, a liquid resin, and a powdery curing agent;

laminating a conductor foil or a second wiring layer supported by a second supporting base onto a surface of said insulating base where said first wiring layer is not placed ; and

5 laminating and integrating said first wiring layer, said insulating base, and said conductor foil / said second wiring layer by pressurizing in a thickness direction thereof, and allowing said liquid resin contained in said conductor to leak out into a gap between said first wiring  
10 layer and said insulating base and into a gap between said conductor foil / said second wiring layer and said insulating base.

12. A manufacturing method of a circuit substrate, comprising the steps of:

15 forming a through hole in an insulating base;  
filling said through hole with a conductor containing a conductive powder, a liquid resin, and a powdery curing agent;

laminating a wiring layer in which one surface  
20 thereof is supported by a supporting base, onto at least one surface of said insulating base via an adhesive layer from an another surface side thereof; and

laminating and integrating said wiring layer and said insulating base by pressurizing in a thickness direction  
25 thereof, and allowing said liquid resin contained in said conductor to leak out into a gap between said wiring layer and said insulating base.